

Abdolreza Geranmayeh

List of Publications by Year in descending order

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41
papers

1,066
citations

361413

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32
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42
docs citations

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times ranked

542
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|--|-----|-----------|
| 1 | Impression creep behavior of lead-free Sn-5Sb solder alloy. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2007, 448, 287-293. | 5.6 | 74 |
| 2 | Indentation creep of lead-free Sn-9Zn and Sn-8Zn-3Bi solder alloys. <i>Materials & Design</i> , 2009, 30, 574-580. | 5.1 | 72 |
| 3 | High-temperature shear strength of lead-free Sn-Sb-Ag/Al ₂ O ₃ composite solder. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2011, 528, 3967-3972. | 5.6 | 63 |
| 4 | Microstructure and impression creep behavior of lead-free Sn-5Sb solder alloy containing Bi and Ag. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2012, 547, 110-119. | 5.6 | 56 |
| 5 | Interlaminar shear strength and tensile properties of environmentally-friendly fiber metal laminates reinforced by hybrid basalt and jute fibers. <i>Polymer Testing</i> , 2019, 75, 205-212. | 4.8 | 49 |
| 6 | Room-temperature indentation creep of lead-free Sn-5%Sb solder alloy. <i>Journal of Electronic Materials</i> , 2005, 34, 1002-1009. | 2.2 | 47 |
| 7 | Power law indentation creep of Sn-5% Sb solder alloy. <i>Journal of Materials Science</i> , 2005, 40, 3361-3366. | 3.7 | 47 |
| 8 | Impression creep of hypoeutectic Sn-Zn lead-free solder alloys. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2008, 491, 110-116. | 5.6 | 47 |
| 9 | Effect of Li content on the indentation creep characteristics of cast Mg-Li-Zn alloys. <i>Materials & Design</i> , 2015, 75, 184-190. | 5.1 | 47 |
| 10 | Impression creep behavior of cast Pb-Sb alloys. <i>Journal of Alloys and Compounds</i> , 2007, 427, 124-129. | 5.5 | 46 |
| 11 | Indentation creep study of lead-free Sn-5%Sb solder alloy. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2007, 457, 173-179. | 5.6 | 46 |
| 12 | Room-temperature indentation creep of lead-free Sn-Bi solder alloys. <i>Journal of Materials Science: Materials in Electronics</i> , 2007, 18, 1071-1078. | 2.2 | 40 |
| 13 | Enhanced superplasticity in equal-channel angularly pressed Sn-5Sb alloy. <i>Scripta Materialia</i> , 2011, 64, 521-524. | 5.2 | 40 |
| 14 | A comparative study on the effects of Gd, Y and La rare-earth elements on the microstructure and creep behavior of AZ81 Mg alloy. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2020, 790, 139712. | 5.6 | 37 |
| 15 | Effect of cooling rate on the room-temperature impression. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2008, 487, 20-25. | 5.6 | 35 |
| 16 | Impression creep study of a Cu-0.3Cr-0.1Ag alloy. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2010, 527, 2702-2708. | 5.6 | 31 |
| 17 | Impression Creep of a Lead-Free Sn-1.7Sb-1.5Ag Solder Reinforced by Submicron-Size Al ₂ O ₃ Particles. <i>Journal of Electronic Materials</i> , 2010, 39, 215-222. | 2.2 | 26 |
| 18 | Effect of cooling rate on the room-temperature indentation creep of cast lead-free Sn-Bi solder alloys. <i>Physica Status Solidi (A) Applications and Materials Science</i> , 2007, 204, 2302-2308. | 1.8 | 22 |

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|----|---|-----|-----------|
| 19 | Effect of Homogenization on the Indentation Creep of Cast Lead-Free Sn-5%Sb Solder Alloy. Journal of Electronic Materials, 2007, 36, 1703-1710. | 2.2 | 20 |
| 20 | Compressive and impression creep behavior of a cast Mg-Al-Zn-Si alloy. Materials Chemistry and Physics, 2013, 139, 79-86. | 4.0 | 20 |
| 21 | Effect of rare earth element additions on the impression creep of Sn-9Zn solder alloy. Journal of Materials Science: Materials in Electronics, 2010, 21, 58-64. | 2.2 | 19 |
| 22 | Indentation creep of a cast Mg-Al-Zn-0.7Si alloy. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2014, 614, 311-318. | 5.6 | 18 |
| 23 | Indentation creep of lead-free Sn-3.5Ag solder alloy: Effects of cooling rate and Zn/Sb addition. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2013, 565, 236-242. | 5.6 | 17 |
| 24 | A comparison of impression, indentation and impression-relaxation creep of lead-free Sn-9Zn and Sn-8Zn-3Bi solders at room temperature. Journal of Materials Science: Materials in Electronics, 2009, 20, 312-318. | 2.2 | 16 |
| 25 | Impression creep behavior of a Cu-Ni-Mn-Sn-Al alloy. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2012, 535, 202-208. | 5.6 | 16 |
| 26 | Effect of stacking sequence on the mechanical properties of pseudo-ductile thin-ply unidirectional carbon-basalt fibers/epoxy composites. Journal of Industrial Textiles, 2022, 51, 2835S-2852S. | 2.4 | 15 |
| 27 | Effects of Ag and Al Additions on the Structure and Creep Properties of Sn-9Zn Solder Alloy. Journal of Electronic Materials, 2009, 38, 330-337. | 2.2 | 13 |
| 28 | The Effect of Different Configurations on the Bending and Impact Properties of the Laminated Composites of Aluminum-Hybrid Basalt and Jute Fibers-Epoxy. Fibers and Polymers, 2019, 20, 1054-1060. | 2.1 | 13 |
| 29 | The Temperature Effects on the Mechanical Properties of Pseudo-ductile Thin-ply Unidirectional Carbon-basalt Fibers/Epoxy Hybrid Composites with Different Stacking Sequences. Fibers and Polymers, 2021, 22, 3162-3171. | 2.1 | 13 |
| 30 | Creep of dilute tin based lead free solder alloys as replacements of Sn-Pb solders. Materials Science and Technology, 2008, 24, 803-808. | 1.6 | 10 |
| 31 | Impression creep of the rare-earth doped Sn-2%Bi lead-free solder alloy. Journal of Materials Science: Materials in Electronics, 2010, 21, 262-269. | 2.2 | 10 |
| 32 | Indentation Creep of Lead-Free Sn-5Sb Solder Alloy with 1.5Åwt% Ag and Bi Additions. Journal of Electronic Materials, 2014, 43, 717-723. | 2.2 | 10 |
| 33 | Effect of Zn and Sb Additions on the Impression Creep Behavior of Lead-Free Sn-3.5Ag Solder Alloy. Journal of Electronic Materials, 2016, 45, 764-770. | 2.2 | 9 |
| 34 | A comparative study of room-temperature creep in lead-free tin-based solder alloys. International Journal of Materials Research, 2010, 101, 271-278. | 0.3 | 8 |
| 35 | Creep Behavior of Copper and Cu-0.3Cr-0.1Ag Alloy. Journal of Engineering Materials and Technology, Transactions of the ASME, 2010, 132, . | 1.4 | 5 |
| 36 | Effect of isothermal aging on room temperature impression creep of lead free Sn-9Zn and Sn-8Zn-3Bi solders. Materials Science and Technology, 2010, 26, 1001-1007. | 1.6 | 4 |

| # | ARTICLE | IF | CITATIONS |
|----|---|-----|-----------|
| 37 | A comparison of mechanical characteristics of four common orthodontic loops in different ranges of activation and angular bends: The concordance between experiment and finite element analysis. <i>International Orthodontics</i> , 2018, 16, 42-59. | 1.9 | 2 |
| 38 | High-temperature shear strength and hardness of cast lead-free solders. <i>Metallic Materials</i> , 2017, 55, 211-216. | 0.3 | 2 |
| 39 | Creep of lead-free Sn-3.8Ag and Sn-3.8Ag-0.7Cu solder alloy as replacements of Sn-Pb solder used in microelectronic packaging. , 2008, , . | | 1 |
| 40 | Indentation creep of lead-free Sn-Bi solder alloys as replacements of Sn-Pb used in microelectronic packaging. <i>Electronics Manufacturing Technology Symposium (IEMT), IEEE/CPMT International</i> , 2006, , . | 0.0 | 0 |
| 41 | Indentation creep behaviour of the magnesium AZ61â€“0.7Siâ€“ <i>i>x</i></i> Bi cast alloys. <i>Materials Science and Technology</i> , 2022, 38, 1195-1205. | 1.6 | 0 |